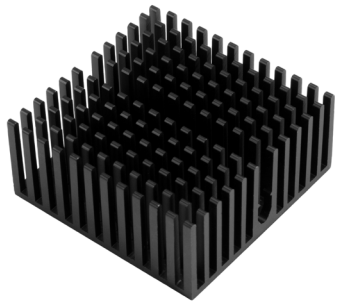
MODEL: HSB16-404018 | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- top mount
- aluminum alloy
- black anodized finish



RoHS

MODEL

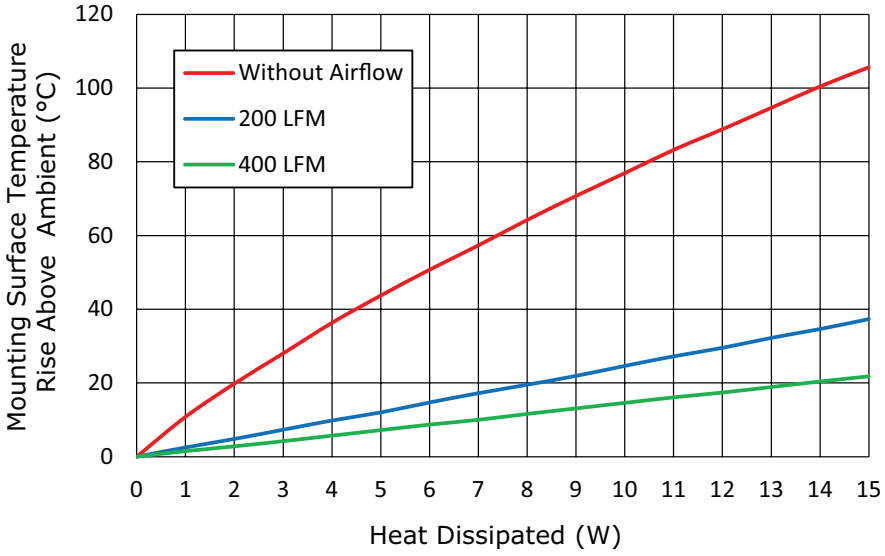
MODEL	thermal resistance[1] @ 75°C ΔT, nat conv (°C/W)	thermal resistance[1] @ 1 W, nat conv (°C/W)	thermal resistance[1] @ 1 W, 200 LFM (°C/W)	thermal resistance[1] @ 1 W, 400 LFM (°C/W)	power dissipation[1] @ 75°C ΔT, nat conv (W)
HSB16-404018	7.68	10.8	2.5	1.5	9.77

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	10.8	2.5	1.5
2	19.8	4.8	2.8
3	28.0	7.3	4.2
4	36.3	9.8	5.7
5	43.7	12.0	7.2
6	50.7	14.7	8.7
7	57.3	17.2	10.0
8	64.2	19.5	11.6
9	70.7	21.9	13.1
10	76.9	24.6	14.6
11	83.2	27.2	16.1
12	88.8	29.5	17.4
13	94.6	32.2	18.9
14	100.4	34.6	20.4
15	105.6	37.3	21.8

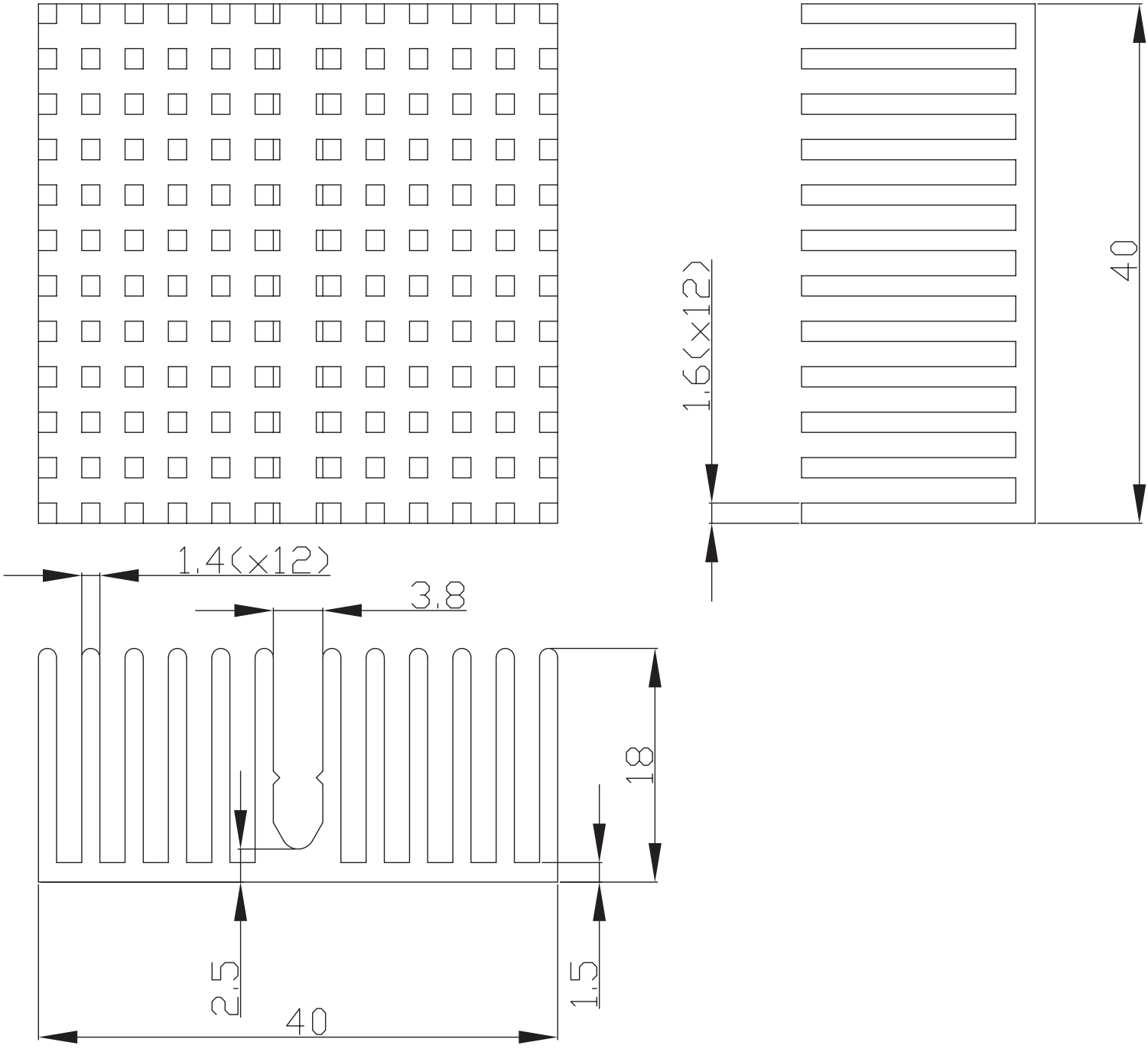
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance:
X.X ±0.10 mm
X.XX ±0.05 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	15.0 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021
1.01	logo, datasheet style update	08/05/2022
1.02	CUI Devices rebranded to Same Sky	09/12/2024
1.03	factory location change	01/21/2026

The revision history provided is for informational purposes only and is believed to be accurate.